L	Hits	Search Text	DB	Time stamp
Number	птсэ		DB	_
1	0	heat\$lindicat\$3 adj (paint strip)	USPAT;	2003/10/18
2	4	 (heat adj indicat\$3 heat\$1indicat\$3) adj	EPO; JPO USPAT;	11:13 2003/10/18
2	4	(paint strip)	EPO; JPO	11:15
3	3	heat adj indicat\$3 with (paint strip	USPAT;	2003/10/18
		material) and heat\$3 and substrate and	EPO; JPO	11:18
4	0	circuit heat adj indicator and temperature and	USPAT;	2003/10/18
1		anneal and heat\$3 and substrate and	EPO; JPO	11:19
		circuit		
5	23	heat\$3 adj1 indicator and temperature and substrate and circuit	USPAT; EPO; JPO	2003/10/18
6	19	("4028118" "4032687" "4142782"	USPAT	2003/10/18
		"4360780" "4379816" "4497881"		11:20
		"4702563" "4702564" "4725462" "4726661" "4727006" "4737020"		
		"4835475" "4835476" "5015544"		
		"5059895" "5156931" "5371657"		
_	100542	"5466654").PN.	IICDAM.	2002/10/19
7	109542	(temperature heat\$3 adj1 indicator) and temperature and substrate and circuit	USPAT; EPO; JPO	2003/10/18
8	201	(temperature heat\$3) adj1 indicator and	USPAT;	2003/10/18
	2.	temperature and substrate and circuit	EPO; JPO USPAT;	11:27
9.	24	((temperature heat\$3) adj1 indicator and temperature and substrate and circuit)	EPO; JPO	11:24
		and anneal\$3		
10	7	(temperature heat\$3) adj1 indicator with	USPAT;	2003/10/18
		(paint\$3 strip) and temperature and substrate and circuit	EPO; JPO	12:43
13	1	(temperature heat\$3) adj1 indicator with	USPAT;	2003/10/18
		(paint\$3 strip) and substrate and circuit	EPO; JPO	12:44
14	15	and (oven furnace) (temperature heat\$3) adj1 indicator with	USPAT;	2003/10/18
		(paint\$3 strip) and substrate and (oven	EPO; JPO	13:32
1.5		furnace)	USPAT	2003/10/18
15	4	5340537.URPN.	OSPAI	13:21
16	11	1 1 2 2 2	USPAT;	2003/10/18
		(paint\$3 strip) and surface with substrate and (oven furnace)	EPO; JPO	13:32
_	2	heating with microelectronic.ti.	USPAT;	2003/09/20
			US-PGPUB	11:19
-	18	heating and microelectronic and oscillat\$3 with electro\$1magnetic and	USPAT; EPO; JPO	2003/09/20
		field	120, 020	
-	26	heat\$3 and microelectronic and oscillat\$3	USPAT;	2003/09/20
_	92	with electro\$1magnetic and field heat\$3 with oscillat\$3 with	EPO; JPO USPAT;	11:24
	, ,,,	electro\$1magnetic with field	EPO; JPO	11:24
-	3	"6150186"	USPAT	2003/09/20
_	100	"5476211"	USPAT	14:35
	100	J., V211	331111	14:39
-	51	"5917707"	USPAT	2003/09/20
_	8	"6336269"	USPAT	14:40 2003/09/20
				14:40
-	272	micro\$1electronic and heat\$3 and cool\$3	USPAT;	2003/10/15
_	95	and oscillat\$3 (micro\$1electronic and heat\$3 and cool\$3	EPO; JPO USPAT;	19:06 2003/10/15
	53	and oscillat\$3) and electro\$1magnetic	EPO; JPO	19:07
-	95	29/\$.ccls. and 219/\$.ccls. and	USPAT;	2003/10/16
_	41	148/\$.ccls. (29/\$.ccls. and 219/\$.ccls. and	EPO; JPO USPAT;	13:48 2003/10/16
	1 41	148/\$.ccls.) and heat\$3	EPO; JPO	13:49
-	3	((29/\$.ccls. and 219/\$.ccls. and	USPAT;	2003/10/16
		148/\$.ccls.) and heat\$3) and	EPO; JPO	13:50
L	L	electro\$1magnetic	<u> </u>	<u> </u>

-	3	((29/\$.ccls. and 219/\$.ccls. and	USPAT;	2003/10/16
1		148/\$.ccls.) and heat\$3) and oscillat\$3	EPO; JPO	13:51
i _	4	((29/\$.ccls. and 219/\$.ccls. and	USPAT;	2003/10/16
	_	148/\$.ccls.) and heat\$3) and wave	EPO; JPO	13:54
_	448	(heat\$1treatment heat adj1 treatment) and	USPAT;	2003/10/16
_	440			
	_	electromagnetic adj field	EPO; JPO	14:17
_	305	((heat\$1treatment heat adj1 treatment)	USPAT;	2003/10/16
		and electromagnetic adj field) and	EPO; JPO	13:56
		frequency		
_	64	(((heat\$1treatment heat adj1 treatment)	USPAT;	2003/10/16
		and electromagnetic adj field) and	EPO; JPO	14:16
		frequency) and cool\$3 and substrate	Ero, oro	14.10
				2002/10/16
_	466	(heat\$1treatment heat adj1 treatment) and	USPAT;	2003/10/16
		(electromagnetic adj field	EPO; JPO	14:18
		electro\$1magnetic adj field)		
_	39	((heat\$1treatment heat adj1 treatment)	USPAT;	2003/10/16
		and (electromagnetic adj field	EPO; JPO	14:41
		electro\$1magnetic adj field)) and	220, 020	
		generat\$3 and resonant adj frequency		
	104		****	2002/10/16
-	124	oscillating adj electromagnetic adj field	USPAT;	2003/10/16
1		and heat\$3	EPO; JPO	15:08
-	4	(oscillating adj electromagnetic adj	USPAT;	2003/10/16
1		field and heat\$3) and micro\$1electronic	EPO; JPO	15:09
-	898	heat\$3 and cool\$3 and micro\$1electronic	USPAT;	2003/10/16
		and substrate and frequency and	EPO; JPO	15:10
		temperature		
- -	420	l ±	IIGDAT.	2003/10/16
-	429	heat\$3 and cool\$3 and micro\$1electronic	USPAT;	, ,
		and substrate and frequency and metallic	EPO; JPO	15:11
		and temperature		
-	75	(heat\$3 and cool\$3 and micro\$1electronic	USPAT;	2003/10/16
		and substrate and frequency and metallic	EPO; JPO	15:38
		and temperature) and oven		
_	55	(oscillating adj electromagnetic adj	USPAT;	2003/10/16
		field and heat\$3) and cool\$3 and	EPO; JPO	15:40
		temperature	EFO, OFO	13.40
	151		IICDAM.	2002/10/16
-	151	(heat\$3 and cool\$3 and micro\$1electronic	USPAT;	2003/10/16
		and substrate and frequency and metallic	EPO; JPO	15:41
		and temperature) and microwave		
-	4	("2903543" "4522834" "4974503"	USPAT	2003/10/16
	1	"4980530").PN.		16:31
_	2	("4978501" "5035858").PN.	USPAT	2003/10/16
	_	, , , , , , , , , , , , , , , , , , , ,		16:59
	4	("4422442" "4801343" "5047605"	USPAT	2003/10/16
_	4		OSENI	17:05
	1	"5994680").PN.	TTCD2m	!
-	435	micro\$1electronic and anneal\$3 and	USPAT;	2003/10/16
	1	(electro\$1magnetic microwave)	EPO; JPO	17:23
-	256	micro\$1electronic and anneal\$3 and	USPAT;	2003/10/16
		(electro\$1magnetic microwave) and	EPO; JPO	17:24
		frequency		
_	59	(micro\$1electronic and anneal\$3 and	USPAT;	2003/10/16
		(electro\$1magnetic microwave) and	EPO; JPO	17:32
		frequency) and spring	,	- · · ·
_	68	(micro\$lelectronic and anneal\$3 and	USPAT;	2003/10/16
_	68		· ·	
1.		(electro\$1magnetic microwave) and	EPO; JPO	18:02
		frequency) and resonant		
-	235	148/525,565.ccls. and heat\$3 and cool\$3	USPAT;	2003/10/16
	<u> </u> -		EPO; JPO	18:04
-	1	(148/525,565.ccls. and heat\$3 and cool\$3)	USPAT;	2003/10/16
1	1	and micro\$1electronic	EPO; JPO	18:03
1 _	36	148/525,565.ccls. and heat\$3 and	USPAT;	2003/10/16
[electro\$1magnetic	EPO; JPO	18:10
1_			t I	
-	6	("2491134" "3615924" "3660630"	USPAT	2003/10/16
1		"4181845" "4312685" "4420346").PN.		18:07
-	8	4872926.URPN.	USPAT	2003/10/16
				18:08
-	205	219/602,605,615,616,632,635,636,764,765,77	Dugeas;	2003/10/16
		and heat\$3 and electro\$1magnetic	EPO; JPO	18:16
_	0	(219/602,605,615,616,632,635,636,764,765,7		2003/10/16
	1			l .
1		and heat\$3 and electro\$1magnetic) and	EPO; JPO	18:12
	1	micro\$1electronic	I	İ

151 (219/602,605,615,616,632,635,636,764,765,7058ATS 2003/10/16 and heat33 and electros/magnetic) and property and test property and					
1	-	151		1	2003/10/16
and heat\$3 and electro\$imagnetic) and frequency and tun\$3 electro\$imagnetic					18:12
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- 24 29/dig\$.ccls. and heat\$3 and microwave 29/dig\$.ccls. and heat\$3 and microwave 29/dig\$.ccls. and heat\$3 and microwave 156/5.ccls. and heat\$3 and heat\$3 and microwave 156/5.ccls. and heat\$3 and heat\$3 and heat\$3 with treat\$4 and frequency and resonant and tun\$4 156/5.ccls. and heat\$3 and heat\$3 with treat\$4 and frequency 156/5.ccls. and heat\$3 and heat\$3 with treat\$4 frequency 156/5.ccls. and heat\$3 and heat\$3 with treat\$4 frequency 156/5.ccls. and heat\$3 and heat\$3 with treat\$4 frequency 156/5.ccls. and anneal\$3 and heat\$3 and heat\$3 with treat\$4 frequency 156/5.ccls. and anneal\$3 and heat\$3 and heat\$3 with treat\$4 frequency 156/5.ccls. and anneal\$3 and heat\$3 and heat\$3 and heat\$3 with treat\$4 frequency 156/5.ccls. and anneal\$3 and heat\$3	-			1	
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9 29/dig\$.ccls. and heat\$3 and microwave LSPAR; 19:42 19:42 10:45 19:45	-	24			
1566 156/\$.ccls. and heat\$3 and microwave USPAT; 2003/10/16 2014 2015				1 '	1
1566 156/\$.ccls. and heat\$3 and microwave 1870; JPO 19:50 19	-	9	29/dig\$.ccls. and heat\$3 and microwave		
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The content of the	-	1566	156/\$.ccls. and heat\$3 and microwave		
and microelectronic	1			EPO; JPO	19:50
- 68	-	78	(156/\$.ccls. and heat\$3 and microwave)	USPAT;	2003/10/16
and microelectronic) and frequency			and microelectronic	EPO; JPO	19:43
and microelectronic) and frequency	-	68	((156/\$.ccls. and heat\$3 and microwave)	USPAT;	2003/10/16
-	1			EPO; JPO	19:43
and microelectronic) and frequency) and electros/lmagnetic 10 156/\$.ccls. and heat\$3 and electros/lmagnetic and anneal\$3 and cool\$3 and metallic adj material 39 electromagnetic and anneal\$3 and heat\$3 uspAT; with treat\$4 and frequency and resonant and tun\$4 (electromagnetic and anneal\$3 and heat\$3 uspAT; 2003/10/16 EPO; JPO 20:14 30 (electromagnetic and anneal\$3 and heat\$3 uspAT; electromagnetic same and resonant and tun\$4 uspAT; electromagnetic same heat\$3 same (structure device) and anneal\$3 and heat\$3 uspAT; electromagnetic same heat\$3 same (structure device) and anneal\$3 and heat\$3 uspAT; electromagnetic same heat\$3 same (structure device) and anneal\$3 and heat\$3 uspAT; electromagnetic same heat\$3 same (structure device) and anneal\$3 and heat\$3 uspAT; electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 uspAT; electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 uspAT; electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 uspAT; electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 uspAT; electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 uspAT; electromagnetic same heat\$1 uspAT; 2003/10/16 EPO; JPO 20:42 USPAT; 2003/10/17 EPO; JPO 10:00 USPAT; 2003/10/17 EPO; JPO 10:00 USPAT; 2003/10/17 EPO; JPO 10:00 USPAT; 2003/10/17 EPO; JPO 10:05 USPAT; 2003/10/17 EPO; JPO 10:05 USPAT; 2003/10/17 EPO; JPO 10:05 USPAT; 2003/10/17 EPO; JPO 10:06 USPAT; 2003/10/17 EPO; JPO 10:05 USPAT; 2003/10/17 EPO; JPO 10:06 USPAT; 2003/10	_	31			2003/10/16
electro\$Imagnetic	1			· ·	1
10 156/\$.ccls. and heat\$3 and electro\$lmagnetic and anneal\$3 and cool\$3 and metallic adj material electromagnetic and anneal\$3 and heat\$3 uspAT; 2003/10/16 EPO; JPO 20:19 and tun\$4 uspAT; 2003/10/16 EPO; JPO 20:14 and tun\$4 uspAT; EPO; JPO 20:14 and tun\$4 uspAT; EPO; JPO 20:14 and tun\$4 uspAT; EPO; JPO 20:11 and tun\$4 uspAT; uspAT; 2003/10/16 EPO; JPO 20:11 and tun\$4 uspAT; EPO; JPO 20:15 and tun\$4 uspAT;	1			,	
electro%lmagnetic and anneal\$3 and cool\$3 EPO; JPO 20:09 and metallic adj material USPAT; 2003/10/16 EPO; JPO 20:14 and tun\$4 and (device structure) electromagnetic same heat\$3 same (structure device) and anneal\$3 and heat\$3 and heat\$3 with treat\$4 frequency electromagnetic same heat\$3 same (structure device) and anneal\$3 and heat\$3 with treat\$4 and frequency electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 uspAT; 2003/10/16 EPO; JPO 20:41 and treat\$4 electromagnetic same heat\$3 same uspAT; 2003/10/16 EPO; JPO 20:42 and treat\$4 and metallic adj material unductive adj heating unductive unduc	_	10		USPAT:	2003/10/16
and metallic adj material electromagnetic and anneal\$3 and heat\$3 with treat\$4 and frequency and resonant and tun\$4 (electromagnetic and anneal\$3 and heat\$3 with treat\$4 and frequency and resonant and tun\$4) and (device structure) electromagnetic same heat\$3 same (structure device) and anneal\$3 and heat\$3 with treat\$4 frequency electromagnetic same heat\$3 same (structure device) and anneal\$3 and heat\$3 with treat\$4 frequency electromagnetic same heat\$3 same (structure device) and anneal\$3 and heat\$3 with treat\$4 frequency electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4 (electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4 (electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4 (electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4) and metallic adj material inductive adj heating 2456 2456 (inductive adj heating) and micro\$lelectronic (inductive adj heating) and non\$lmetallic adj substrate (inductive adj heating) and hairpin adj coil (inductive adj heating) and hairpin adj coil (inductive adj heating) and resonant adj frequency (inductive adj heating) and resonant adj frequency) and ferromagnetic (inductive adj heating) and resonant adj frequency) and ferromagnetic (inductive adj heating) and resonant adj frequency) and ferromagnetic (inductive adj heating) and electromagnetic adj field) ((inductive adj heating) and electromagnetic adj field) ((inductive adj heating) and electromagnetic adj field) and heat\$3 and espo; JPO 10:25 1003/10/16 EPO; JPO 10:12 1003/10/17 EPO; JPO 10:25 1003/10/17 EPO; JPO 10	1				' '
- 39 electromagnetic and anneal\$3 and heat\$3 with treat\$4 and frequency and resonant and tun\$4 - 30 (electromagnetic and anneal\$3 and heat\$3 with treat\$4 and frequency and resonant and tun\$4 with treat\$4 and frequency and resonant and tun\$4 and (device structure) - 925595 electromagnetic same heat\$3 same	1			110, 010	20.05
## with treat\$4 and frequency and resonant and tun\$4 - 30 (electromagnetic and anneal\$3 and heat\$3 with treat\$4 and frequency and resonant and tun\$4) and (device structure) - 925595 electromagnetic same heat\$3 same (structure device) and anneal\$3 and heat\$3 with treat\$4 frequency - 67 electromagnetic same heat\$3 same (structure device) and anneal\$3 and heat\$3 with treat\$4 frequency - 614 (structure device) and anneal\$3 and heat\$3 with treat\$4 and frequency - 614 (structure device) and anneal\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4 and frequency - 614 (structure device) and cool\$3 and heat\$3 with treat\$4 (electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4 (alectromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4 and metallic adj material inductive adj heating) and micro\$lelectronic (inductive adj heating) and non\$lmetallic adj substrate (inductive adj heating) and heat\$1 uspat; 2003/10/17 epo; JPO 10:05 - 0 (inductive adj heating) and hair\$1pin adj coil (inductive adj heating) and resonant adj frequency ((inductive adj heating) and resonant adj frequency ((inductive adj heating) and resonant adj frequency ((inductive adj heating) and electromagnetic adj field) and heat\$3 and epo; JPO 10:12 uspat; 2003/10/17 epo; JPO 10:11 uspat; 2003/10/17 epo; JPO 10:11 uspat; 2003/10/17 epo; JPO 10:05 uspat; 2003/10/17 epo; JPO 10:11 uspat; 2003/10/17 epo; JPO 10:12 uspat; 2003/10/17 epo; JPO 10:25 uspat; 2003/10/17 epo;	1_	30		HCDAT.	2003/10/16
and tuns4	-	39			
SPAT; 2003/10/16 EPO; JPO 20:11				EPO; JPO	20:14
with treat\$4 and frequency and resonant and tun\$4 and (device structure)		20	· ·	************	2002/10/16
and tun\$4) and (device structure) electromagnetic same heat\$3 same (structure device) and anneal\$3 and heat\$3 with treat\$4 frequency electromagnetic same heat\$3 same (structure device) and anneal\$3 and heat\$3 with treat\$4 frequency electromagnetic same heat\$3 same (structure device) and anneal\$3 and heat\$3 with treat\$4 and frequency electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4 4 (electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4 and frequency with treat\$4 and frequency electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4 and metallic adj material inductive adj heating 2456 2456 (inductive adj heating) and micro\$ielectronic (inductive adj heating) and non\$lmetallic adj substrate (inductive adj heating) and hairpin adj coil (inductive adj heating) and hairpin adj coil (inductive adj heating) and hairpin adj frequency (inductive adj heating) and resonant adj electromagnetic adj field electromagnetic adj field electromagnetic adj field electromagnetic adj field)	-	30			
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Control Cont	1			EPO; JPO	20:15
(structure device) and anneal\$3 and heat\$3 with treat\$4 and frequency electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4 (electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4 (electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4) and metallic adj material inductive adj heating USPAT; 2003/10/17 EPO; JPO 20:42 USPAT; 2003/10/17 EPO; JPO 10:00 USPAT; 2003/10/17 EPO; JPO 10:00 USPAT; 2003/10/17 EPO; JPO 10:04 USPAT; 2003/10/17 EPO; JPO 10:05 USPAT; 2003/10/17 EPO; JPO 10:06 USPAT; 2003/10/17 EPO; JPO 10:06 USPAT; 2003/10/17 EPO; JPO 10:06 USPAT; 2003/10/17 EPO; JPO 10:11 USPAT; 2003/10/17 EPO; JPO 10:12 USPAT; 2003/10					
heat\$3 with treat\$4 and frequency electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4 (electromagnetic same heat\$3 same uspat; 2003/10/16 EPO; JPO 20:42 with treat\$4 (electromagnetic same heat\$3 same uspat; 2003/10/16 EPO; JPO 20:42 with treat\$4 and metallic adj material uspat; 2003/10/17 EPO; JPO 20:42 with treat\$4 and metallic adj material uspat; 2003/10/17 EPO; JPO 10:00 uspat; 2003/10/17 EPO; JPO 10:00 uspat; 2003/10/17 EPO; JPO 10:05 uspat; 2003/10/17 EPO; JPO 10:06 uspat; 2003/10/17 EPO; JPO 10:06 uspat; 2003/10/17 EPO; JPO 10:11 uspat; 2003/10/17 EPO; JPO 10:12 uspat; 2003/10/17 EPO; JPO uspat; 2003/1	-	67		,	
- 614 electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4 (electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4 (electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4) and metallic adj material inductive adj heating USPAT; 2003/10/17 EPO; JPO 10:00 - 23 (inductive adj heating) and USPAT; 2003/10/17 EPO; JPO 10:04 USPAT; 2003/10/17 EPO; JPO 10:05 USPAT; 2003/10/17 EPO; JPO 10:06 USPAT; 2003/10/17 EPO; JPO 10:11 USPAT; 2003/10/17 EPO; JPO 10:12 USPAT; 2003/10/17 EPO; JPO 10:25				EPO; JPO	20:41
(structure device) and cool\$3 and heat\$3 EPO; JPO 20:42 with treat\$4 (electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4) and metallic adj material uspat; 2003/10/17 EPO; JPO 20:42 20:	-				
With treat\$4	-	614	electromagnetic same heat\$3 same	USPAT;	2003/10/16
With treat\$4	1			EPO; JPO	20:42
- 44 (electromagnetic same heat\$3 same (structure device) and cool\$3 and heat\$3 with treat\$4) and metallic adj material inductive adj heating	1	t			
with treat\$4) and metallic adj material inductive adj heating	-	44	(electromagnetic same heat\$3 same	USPAT;	2003/10/16
with treat\$4) and metallic adj material inductive adj heating			(structure device) and cool\$3 and heat\$3	EPO; JPO	20:42
- 2456 inductive adj heating - 23 (inductive adj heating) and micro\$1electronic - 0 (inductive adj heating) and non\$1metallic adj substrate - 0 (inductive adj heating) and hairpin adj coil - 0 (inductive adj heating) and hairpin adj coil - 0 (inductive adj heating) and hair\$1pin adj coil - 0 (inductive adj heating) and resonant adj frequency - 22 ((inductive adj heating) and resonant adj frequency) and ferromagnetic frequency and ferromagnetic adj field - 231 (inductive adj heating) and electromagnetic adj field) and heat\$3 and epo; JPO 10:25					
- 23 (inductive adj heating) and micro\$1electronic	-	2456		USPAT;	2003/10/17
- 23 (inductive adj heating) and micro\$1electronic					
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- 0 (inductive adj heating) and non\$1metallic adj substrate - 0 (inductive adj heating) and hairpin adj coil - 0 (inductive adj heating) and hair\$1pin adj coil - 0 (inductive adj heating) and hair\$1pin adj coil - 99 (inductive adj heating) and resonant adj frequency - 22 ((inductive adj heating) and resonant adj frequency) and ferromagnetic - 231 (inductive adj heating) and electromagnetic adj field - 50 ((inductive adj heating) and electromagnetic adj field) and heat\$3 and EPO; JPO 10:25	1	23		· ·	
adj substrate (inductive adj heating) and hairpin adj coil (inductive adj heating) and hair\$1pin adj coil (inductive adj heating) and hair\$1pin adj coil 99 (inductive adj heating) and resonant adj frequency ((inductive adj heating) and resonant adj frequency) and ferromagnetic 22 ((inductive adj heating) and resonant adj frequency) and ferromagnetic 231 (inductive adj heating) and electromagnetic adj field ((inductive adj heating) and electromagnetic adj field) and heat\$3 and EPO; JPO 10:05 USPAT; 2003/10/17 EPO; JPO 10:11 USPAT; 2003/10/17 EPO; JPO 10:12 USPAT; 2003/10/17 EPO; JPO 10:12 USPAT; 2003/10/17 EPO; JPO 10:12 TEPO; JPO 10:12	_	_			
- 0 (inductive adj heating) and hairpin adj coil - 0 (inductive adj heating) and hairslpin adj coil - 99 (inductive adj heating) and resonant adj frequency - 22 ((inductive adj heating) and resonant adj frequency) and ferromagnetic - 231 (inductive adj heating) and electromagnetic adj field - 50 ((inductive adj heating) and electromagnetic adj field) and heat\$3 and epo; JPO 10:25	1	1		,	
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- 0 (inductive adj heating) and hair\$1pin adj coil - 99 (inductive adj heating) and resonant adj frequency - 22 ((inductive adj heating) and resonant adj frequency) and ferromagnetic - 231 (inductive adj heating) and electromagnetic adj field - 50 ((inductive adj heating) and electromagnetic adj field) and heat\$3 and EPO; JPO 10:25	-				
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frequency) and ferromagnetic (inductive adj heating) and electromagnetic adj field ((inductive adj heating)) and electromagnetic adj field) ((inductive adj heating)) and electromagnetic adj field)) and heat\$3 and EPO; JPO 10:25	1				
- 231 (inductive adj heating) and USPAT; 2003/10/17 electromagnetic adj field EPO; JPO 10:12 USPAT; 2003/10/17 electromagnetic adj field) and heat\$3 and EPO; JPO 10:25	-	22			1
electromagnetic adj field EPO; JPO 10:12 ((inductive adj heating) and USPAT; 2003/10/17 electromagnetic adj field) and heat\$3 and EPO; JPO 10:25	1				1
- 50 ((inductive adj heating) and USPAT; 2003/10/17 electromagnetic adj field) and heat\$3 and EPO; JPO 10:25	-	231			
electromagnetic adj field) and heat\$3 and EPO; JPO 10:25	1				
	-	50	((inductive adj heating) and	USPAT;	2003/10/17
	1		electromagnetic adj field) and heat\$3 and	EPO; JPO	10:25

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-	145		272954"	"2429819" "3466528"	USPAI	10:13
		- ·	74031"	"3609104"		10.13
		•	557038"	"3671371"		
		· · · · · · · · · · · · · ·	733231"	"3737611"		
			746825"	"3816690" i		
			33439"	"3845268" i		
			02940"	"3953700" i		
		"3953783" "39	996402"	"4017701"		
		"4018642" "40	29837"	"4038120"		
		"4112286" "41	20712"	"4123305"		
		"4177494" "42	234824"	"4268737"		
		"4277667" "42	280038"	"4293363"		
		"4327268" "43	355222"	"4382275"		
		"4410457" "44	120876"	"4467165"		
		•	183896"	"4506131"		
			16104"	"4521659"		1
			43555"	"4567094"		
		•	81158"	"4602139"		
			550947"	"4654495"		
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			762864"	"4763093"		
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		•	345332" 397518"	"4847746" "4941936"		
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			983804"	"5025123" I		
			31088"	"5057370" I		
			93545"	"5123989"		
		•	28504"	"5134000"		
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			376403"	"5378879"		
			38181"	"5483043"		
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		•	34097"	"5573613"		
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		•	723849"	"5773799" "5837088"		
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			925455"	"5932057"		
		•)43471"	"6056844"		
		"RE36787" "60		•		
		"6110565" "61				
		"6302178").PN.		, , , , , , , , , , , , , , , , , , , ,		
-	73	((inductive ad	heating	g) and	USPAT;	2003/10/17
		electromagnetic	adj fie	eld) and heat\$3	EPO; JPO	10:39
		with (electroni	ic circui	it)		
-	6	((inductive adj			USPAT;	2003/10/17
				eld) and heat\$3	EPO; JPO	10:49
	_	with electronic	c with (device circuit)		000045545
-	9	4996405.URPN.			USPAT	2003/10/17
						10:40
-	26	((inductive adj			USPAT;	2003/10/17
			adj fie	eld) and heat\$3 adj	EPO; JPO	10:52
	227	treat\$4		trustume and beater	IICDAM.	2002/10/17
_	221	microelectronic adj treat\$4	WICH ST	tructure and heat\$3	USPAT; EPO; JPO	2003/10/17 10:53
_	207	adj treat\$4 (microelectroni	ic with	structure and	USPAT;	2003/10/17
-	207	heat\$3 adj trea			EPO; JPO	10:53
_	84	((microelectron			USPAT;	2003/10/17
	"			d substrate) and	EPO; JPO	10:53
		metallic	LUTI/ GII	a substate, and	110, 010	
_	68		onic with	n structure and	USPAT;	2003/10/17
	1			d substrate) and	EPO; JPO	10:54
		metallic) and i			,	
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-	11	("2762892" "3467806" "4327265"	USPAT	2003/10/17
		"4431891" "4642442" "4659912"		14:33
		"4749833" "4771151" "4789767"		
		"4795870" "4806107").PN.		
_	18	4983804.URPN.	USPAT	2003/10/17
		1,5000000000000000000000000000000000000		14:35
_	25	4969968.URPN.	USPAT	2003/10/17
	23	4505500: OKEW:	001111	14:40
	554	heat\$3 and heat\$3 adj treat\$4 and	USPAT;	2003/10/17
_	334	micro\$lelectronic and cool\$3	US-PGPUB;	16:03
		microplerectionic and coorps	EPO; JPO	10.03
	174	0 +00 and base00 and buse400 and		2002/10/17
-	174	(heat\$3 and heat\$3 adj treat\$4 and	USPAT;	2003/10/17
		micro\$1electronic and cool\$3) and	US-PGPUB;	16:03
		substrate and metallic	EPO; JPO	/ /
-	45	((heat\$3 and heat\$3 adj treat\$4 and	USPAT;	2003/10/17
		micro\$1electronic and cool\$3) and	US-PGPUB;	16:12
		substrate and metallic) and	EPO; JPO	
		(electromagnetic oscillat\$4)		
_	0	heat\$3 and cool\$3 and (electromagnetic	USPAT;	2003/10/17
		oscillat\$4) with field and electronic	EPO; JPO	16:14
		with component with heat\$3 with treat\$4		
-	14		USPAT;	2003/10/17
		oscillat\$4) with field and electronic	EPO; JPO	16:14
		with heat\$3 with treat\$4	. ,	
_	22		USPAT	2003/10/17
		"4222023" "4296295" "4549056"		16:58
		"4950348" "5101086" "5208433"		10.00
		"5319179" "5343023" "5352871"		
		"5412184" "5461215" "5466916"		[
		"5504309" "5526561" "5714738"		
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	-	"5919387").PN.	IICDAM	2002/10/17
_	1	6229126.URPN.	USPAT	2003/10/17
1		4500006 ****	******	16:38
-	0	4503306.URPN.	USPAT	2003/10/17
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-	0	4503306.URPN.	USPAT	2003/10/17
				16:53
-	16		USPAT;	2003/10/17
		and spring with structure	EPO; JPO	17:11
-	316		USPAT;	2003/10/17
		and oven	EPO; JPO	17:11
-	210		USPAT;	2003/10/17
		and (oven furnace) and metallic	EPO; JPO	17:13
-	8	microelectronic and heat\$3 adj treat\$4	USPAT;	2003/10/17
		and inductive with heat\$3	EPO; JPO	18:03
-	9	electromagnetic adj field and heat\$3 adj	USPAT;	2003/10/17
		treat\$4 with electronic	EPO; JPO	18:05
 -	26	l · · · · · · · · · · · · · · · · · · ·	USPAT;	2003/10/17
		treat\$4 and inductive adj heat\$3	EPO; JPO	18:08
_	1	electromagnetic adj field and (electric\$2	USPAT;	2003/10/17
1	1	circuit) with (component device) with	EPO; JPO	18:10
		treat\$4 and inductive adj heat\$3	===, ===	
_	92		USPAT;	2003/10/17
	32	circuit) with (component device) and	EPO; JPO	18:10
		inductive adj heat\$3	LEO, UEO	10.10
1	10	inductive adj neat\$3 4983804.URPN.	USPAT	2003/10/17
-	18	1905004.UKPN.	OSFAI	18:14
1	I	/#2762002# #2467006# #4227265#	USPAT	2003/10/17
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_	11	("2762892" "3467806" "4327265"	USIAI	
_	11	"4431891" "4642442" "4659912"	OSTAT	18:17
_	11		OSPAT	

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15	បន	5343023	A	19940830	9	Induction heater having a power inverter and a	219/661	219/663; 219/665;
16	បន	6384339	В1	20020507	11	Printed circuit board assembly having adhesive	174/254	174/259; 361/749
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18	បន	6283358	В1	20010904	12	System for forming contacts on a semiconductor component	228/180.21	228/262.4; 228/49.5;
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22	បន	4028118	A	19770607	20	Thermochromic materials	106/31.19	428/199; 428/29;
23	បន	6188506	В1	20010213	4	Conductive color-changing ink	359/200	
24	បន	6616332	В1	20030909	14	Optical techniques for measuring parameters such as	374/162	116/216; 219/444.1;
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